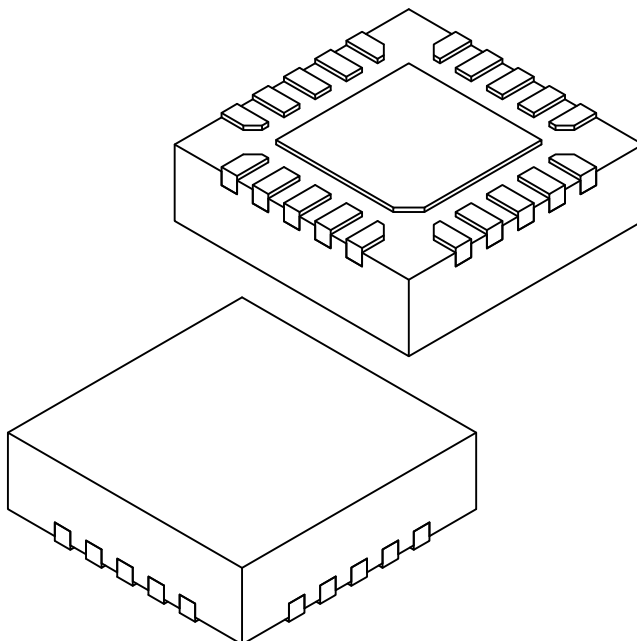


## 20-Lead Very Thin Plastic Quad Flat, No Lead Package (REB) - 3x3 mm Body [VQFN] With 1.7 mm Exposed Pad; Atmel Legacy Global Package Code ZCL

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N		20		
Pitch	e		0.40 BSC		
Overall Height	A	0.80	0.85	0.90	
Standoff	A1	0.00	0.035	0.05	
Terminal Thickness	A3		0.203 REF		
Overall Length	D		3.00 BSC		
Exposed Pad Length	D2	1.60	1.70	1.80	
Overall Width	E		3.00 BSC		
Exposed Pad Width	E2	1.60	1.70	1.80	
Terminal Width	b	0.15	0.20	0.25	
Terminal Length	L	0.35	0.40	0.45	
Terminal-to-Exposed-Pad	K	0.20	-	-	
Pin 1 Index Chamfer	CH		0.35 REF		

**Notes:**

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M
  - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
  - REF: Reference Dimension, usually without tolerance, for information purposes only.